BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-STD





ATS Part#: **ATS-50170P-C1-R0**

Description: 17.00 x 17.00 x 17.50 mm BGA Heat Sink - High Performance maxiFLOW/maxiGRIP-

STD

Heat Sink Type: maxiFLOW

Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-50170P-C2-R0 Discontinued

*Image above is for illustration purpose only.

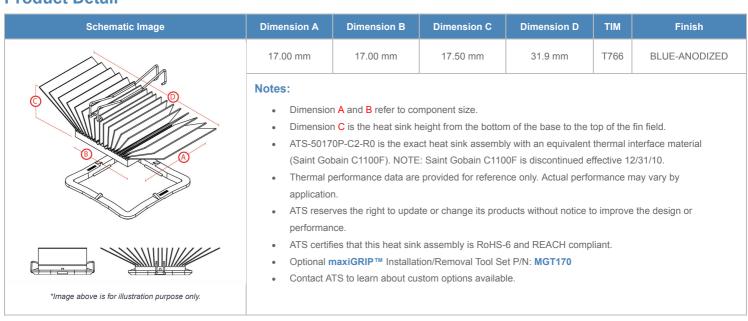
Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- · Comes preassembled with high performance, phase changing, thermal interface material
- Designed for standard height components from 3 to 4.5mm

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	8.3 °C/W	6.9 °C/W	6 °C/W	5.4 °C/W	5 °C/W	4.6 °C/W	4.4 °C/W
	Ducted Flow	6.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail



For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Advanced Thermal Solutions:

ATS-50170P-C1-R0